

Special Issue

Recent Advances in Cooling of Electronic Components

Message from the Guest Editor

This Special Issue of "Recent Advances in Cooling of Electronic Components" will contain the results of the most advanced and latest research. It will particularly focus on the development of new generation heat-dissipated component technology and its performance measurement technology, the application of new materials on the heat-dissipated field, and the development of next-generation heat dissipation component technology. The topics covered in this issue comprise, but are not limited to, the following items:

- Measuring technology for the thermal performance of heat-dissipated elements;
- New technologies for heat conduction and heat dissipation;
- Development of new heat dissipated materials;
- New heat storage systems;
- Cooling technology of electric vehicle motor and battery;
- Graphene and ultra-thin vapor chamber application of 5G mobile phone.

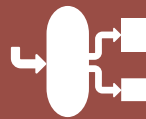
Guest Editor

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Deadline for manuscript submissions

closed (20 May 2022)



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